

MCM10149*25

256 x 4-BIT PROGRAMMABLE READ-ONLY MEMORY

This device is a 256-word x 4-bit field programmable read only memory (PROM). Prior to programming, all stored bits are at logic 1 (high) levels. The logic state of each bit can then be changed by on-chip programming circuitry. The memory has a single negative logic chip enable. When the chip is disabled $(\overline{\text{CS}} = \text{high})$, all outputs are forced to a logic 0 (low).

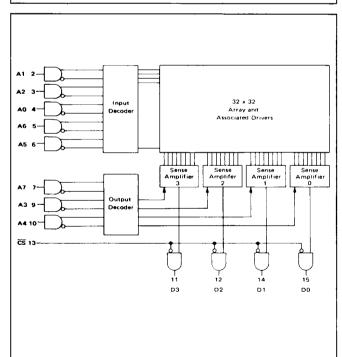
- Typical Address Access Time of 20 ns
- Typical Chip Select Access Time of 8.0 ns
- 50 kΩ Input Pulldown Resistors on All Inputs
- Power Dissipation (540 mW typ @ 25°C)
 Decreases with Increasing Temperature

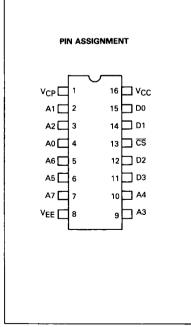
MECL

1024-BIT PROGRAMMABLE READ-ONLY MEMORY



L SUFFIX CERAMIC PACKAGE CASE 620





MCM10149*25

ELECTRICAL CHARACTERISTICS

		0°C		+25°C		+75°C		
Characteristic	Symbol	Min	Max	Min	Max	Min	Max	Unit
Power Supply Drain Current	1EE	-	155	-	150	-	145	mAdc
Input Current High	linH	_	265		265	-	265	μAdc

-55°C and +125°C test values apply to MC105xx devices only.

Forcing Function	Parameter	0°C	25°CÛ	75°C ^①
V _{IHmax} =	V _{OHmax}	-0.840 -1.000	-0.810 -0.960	-0.720 -0.900
	V _{OHAmin}	-1.020	-0.980	-0.920
VIHAmin		-1.130	-1.105	-1.045
VILAmax		-1.490	-1.475	-1.450
	V _{OLAmax}	-1.645	-1.630	-1.605
	V _{OLmax}	1.665	-1.650	-1.625
V _{ILmin} =	V _{OLmin}	-1.870	-1.850	-1.830
VILmin	NLmin	0.5	0.5	0.3

NOTES: ① 0-75°C temperature range, 50Ω to -2.0V.

SWITCHING CHARACTERISTICS (Note 1)

Characteristics		MCM10149*25 T _A = 0 to +75°C, V _{EE} = -5.2 Vdc ±5%			
	Symbol	Min	Max	Unit	Conditions
Read Mode Chip Select Access Time Chip Select Recovery Time Address Access Time	tacs trcs taa	2.0 2.0 7.0	10 10 25	ns	Measured from 50% of input to 50% of output. See Note 1.
Rise and Fall Time	t _F , t _f	1.5	7.0	ns	Measured between 20% and 80% points.
Capacitance Input Capacitance Output Capacitance	C _{in} C _{out}	=	5.0 8.0	pF	Measured with a pulse technique.

NOTES: 1. Test circuit characteristics: $R_T = 50 \Omega$, MCM10149;

C_L ≤ 5.0 pF (including jig and stray capacitance)

- Delay should be derated 30 ps/pF for capacitive load up to 50 pF.

 2. The maximum Address Access Time is guaranteed to be the Worst-Case Bit in the Memory.
- 3. For proper use of MECL Memories in a system environment, consult MECL System Design Handbook.
- 4. VCP = VCC = Gnd for normal operation.

*To be determined; contact your Motorola representative for up-to-date information.

PROGRAMMING THE MCM10149 †

During programming of the MCM 10149, input pins 7, 9, and 10 are addressed with standard MECL 10K logic levels. However, during programming input pins 2, 3, 4, 5, and 6 are addressed with 0 V \leq V $_{IH}$ \leq +0.25 V and V $_{EE}$ \leq V $_{IL}$ \leq -3.0 V. It should be stressed that this deviation from standard input levels is required only during the programming mode. During normal operation, standard MECL 10,000 input levels must be used.

With these requirements met, and with V_{CP} = V_{CC} =

0 V and V $_{EE}$ = - 5.2 V \pm 5%, the address is set up. After a minimum of 100 ns delay, V $_{CP}$ (pin 1) is ramped up to + 12 V \pm 0.5 V (total voltage V $_{CP}$ to V $_{EE}$ is now 17.2 V, + 12 V - [- 5.2 V]). The rise time of this V $_{CP}$ voltage pulse should be in the 1 - 10 μs range, while its pulse width (t $_{W1}$) should be greater than 100 μs but less than 1 ms. The V $_{CP}$ supply current at + 12 V will be approximately 525 mA while current drain from V $_{CC}$ will be approximately 175 mA. A current limit should therefore be

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set on both of these supplies. The current limit on the V_{CP} supply should be set at 700 mA while the V_{CC} supply should be limited to 250 mA. It should be noted that the V_{EE} supply must be capable of sinking the combined current of the V_{CC} and V_{CP} supplies while maintaining a voltage of $-5.2 \ V \pm 5\%$.

Coincident with, or at some delay after the V_{CP} pulse has reached its 100% level, the desired bit to be fused can be selected. This is done by taking the corresponding output pin to a voltage of $+2.85\,V\,\pm\,5\%$. It is to be noted that only one bit is to be fused at a time. The other three unselected outputs should remain terminated through their 50 ohm load resistor to $-2.0\,V$. Current into the selected output is 5.0 mA maximum.

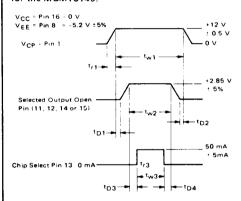
After the bit select pulse has been applied to the appropriate output, the fusing current is sourced out of the chip select pin 13. The 0% to 100% rise time of this current pulse should be 250 ns max. Its pulse width should be greater than 100 μs . Pulse magnitude is 50 mA \pm 5.0 mA. The voltage clamp on this current source is to be $-6.0~\rm V$.

After the fusing current source has returned 0 mA, the bit select pulse is returned to its initial level, i.e., the output is returned through its load to -2.0 V. Thereafter, VCP is returned to 0 V. Strobing of the outputs to determine success in programming should occur no sooner than 100 ns after VCP has returned to 0 V. The remaining bits are programmed in a similar fashion.

† NOTE: For devices that program incorrectly, return serialized units with individual truth tables. Noncompliance voids warranty.

PROGRAMMING SPECIFICATIONS

The following timing diagrams and fusing information represent programming specifications for the MCM10149.



The timing diagram is shown for programming one bit. Note that only one bit is blown at a time. All addressing must be done 100 ns prior to the beginning of the V_{CP} pulse, i.e., $V_{CP} = 0$ V. Likewise, strobing of the outputs to determine success in programming should occur no sooner than 100 ns after V_{CP} returns to 0 V.

Note that the fusing current is defined as a positive current out of the chip select, pin 13. A programming duty cycle of \leq 15% is to be observed.

Definitions and values of timing symbols are as follows

Symbol	Definition	Value
^t r1	Rise Time, Programming Voltage	≥ 1 μs
tw1	Pulse Width, Programming Voltage	\geqslant 100 μ s $<$ 1 ms
^t D1	Delay Time, Programming Voltage Pulse to Bit Select Pulse	≥ 0
t _{w2}	Pulse Width, Bit Select	≥ 100 μs
^t D2	Delay Time, Bit Select Pulse to Programming Voltage Pulse	≥ 0
^t D3	Delay Time, Bit Select Pulse to Programming Current Pulse	≥ 1 μs
^t r3	Rise Time, Programming Current Pulse	250 ns max
t _w 3	Pulse Width, Programming Current Pulse	≥ 100 μs
^t D4	Delay Time, Programming Current Pulse to Bit Select Pulse	≥ 1 μs

